Microchip Technology - DSPIC33EP256MU814-I/PH Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	122
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	12K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 32x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-TQFP
Supplier Device Package	144-TQFP (16x16)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256mu814-i-ph

Pin Diagrams (Continued)

121-Pin TFBGA(1)

● = Pins are up to 5V tolerant

dsPIC33EP256MU810
dsPIC33EP512MU810

	1	2	3	4	5	6	7	8	9	10	11
A	RE4	RE3	RG13	RE0	RG0	RF1	VDD	NC	RD12	RD2	RD1
B	NC	RG15	RE2	RE1	RA7	RF0	VCAP	RD5	RD3	VSS	RC14
C	RE6	VDD	RG12	RG14	RA6	NC	RD7	RD4	NC	RC13	RD11
D	RC1	RE7	RE5	NC	NC	NC	RD6	RD13	RD0	NC	RD10
E	RC4	RC3	RG6	RC2	NC	RG1	NC	RA15	RD8	RD9	RA14
F	$\overline{MCLR}$	RG8	RG9	RG7	VSS	NC	NC	VDD	RC12	VSS	RC15
G	RE8	RE9	RA0	NC	VDD	VSS	VSS	NC	RA5	RA3	RA4
H	RB5	RB4	NC	NC	NC	VDD	NC	VBUS	VUSB3V3	RG2	RA2
J	RB3	RB2	RB7	AVDD	RB11	RA1	RB12	NC	NC	RF8	RG3
K	RB1	RB0	RA10	RB8	NC	RF12	RB14	VDD	RD15	RF3	RF2
L	RB6	RA9	AVSS	RB9	RB10	RF13	RB13	RB15	RD14	RF4	RF5

Note 1: Refer to Table 2 for full pin names.

1.0 DEVICE OVERVIEW

Note 1: This data sheet summarizes the features of the dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 families of devices. It is not intended to be a comprehensive resource. To complement the information in this data sheet, refer to the related section of the "*dsPIC33E/PIC24E Family Reference Manual*", which is available from the Microchip web site (www.microchip.com)

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This document contains device-specific information for the dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 Digital Signal Controller (DSC) and Microcontroller (MCU) devices. The dsPIC33EPXXX(GP/MC/MU)806/810/814 devices contain extensive Digital Signal Processor (DSP) functionality with a high-performance 16-bit MCU architecture.

Figure 1-1 illustrates a general block diagram of the core and peripheral modules in the dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 families of devices.

Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

TABLE 4-9: TIMER1 THROUGH TIMER9 REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TMR1	0100	Timer1 Register																xxxx
PR1	0102	Period Register 1																FFFF
T1CON	0104	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		—	TSYNC	TCS	—	0000
TMR2	0106	Timer2 Register																xxxx
TMR3HLD	0108	Timer3 Holding Register (for 32-bit timer operations only)																xxxx
TMR3	010A	Timer3 Register																xxxx
PR2	010C	Period Register 2																FFFF
PR3	010E	Period Register 3																FFFF
T2CON	0110	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		T32	—	TCS	—	0000
T3CON	0112	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		—	—	TCS	—	0000
TMR4	0114	Timer4 Register																xxxx
TMR5HLD	0116	Timer5 Holding Register (for 32-bit operations only)																xxxx
TMR5	0118	Timer5 Register																xxxx
PR4	011A	Period Register 4																FFFF
PR5	011C	Period Register 5																FFFF
T4CON	011E	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		T32	—	TCS	—	0000
T5CON	0120	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		—	—	TCS	—	0000
TMR6	0122	Timer6 Register																xxxx
TMR7HLD	0124	Timer7 Holding Register (for 32-bit operations only)																xxxx
TMR7	0126	Timer7 Register																xxxx
PR6	0128	Period Register 6																FFFF
PR7	012A	Period Register 7																FFFF
T6CON	012C	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		T32	—	TCS	—	0000
T7CON	012E	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		—	—	TCS	—	0000
TMR8	0130	Timer8 Register																xxxx
TMR9HLD	0132	Timer9 Holding Register (for 32-bit operations only)																xxxx
TMR9	0134	Timer9 Register																xxxx
PR8	0136	Period Register 8																FFFF
PR9	0138	Period Register 9																FFFF
T8CON	013A	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		T32	—	TCS	—	0000
T9CON	013C	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS<1:0>		—	—	TCS	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

5.2 RTSP Operation

The dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 Flash program memory array is organized into rows of 128 instructions or 384 bytes. RTSP allows the user application to erase a page of memory, which consists of eight rows (1024 instructions) at a time, and to program one row or one word at a time. Table 32-12 lists typical erase and programming times. The 8-row erase pages and single row write rows are edge-aligned from the beginning of program memory, on boundaries of 3072 bytes and 384 bytes, respectively.

The program memory implements holding buffers, which are located in the write latch area, that can contain 128 instructions of programming data. Prior to the actual programming operation, the write data must be loaded into the buffers sequentially. The instruction words loaded must always be from a group of 64 boundary.

The basic sequence for RTSP programming is to set up a Table Pointer, then do a series of `TBLWT` instructions to load the buffers. Programming is performed by setting the control bits in the NVMCON register. A total of 128 `TBLWTL` and `TBLWTH` instructions are required to load the instructions.

All of the table write operations are single-word writes (two instruction cycles) because only the buffers are written. A programming cycle is required for programming each row. For more information on erasing and programming Flash memory, refer to **Section 5. "Flash Programming"** (DS70609) in the *"dsPIC33E/PIC24E Family Reference Manual"*.

5.3 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. The processor stalls (waits) until the programming operation is finished.

The programming time depends on the FRC accuracy (see Table 32-19) and the value of the FRC Oscillator Tuning register (see Register 9-4). Use the following formula to calculate the minimum and maximum values for the Row Write Time, Page Erase Time and Word Write Cycle Time parameters (see Table 32-12).

EQUATION 5-1: PROGRAMMING TIME

$$\frac{T}{7.37\ MHz \times (FRC\ Accuracy)\% \times (FRC\ Tuning)\%}$$

For example, if the device is operating at +125°C, the FRC accuracy will be ±5%. If the TUN<5:0> bits (see Register 9-4) are set to `'b111111`, the minimum row write time is equal to Equation 5-2.

EQUATION 5-2: MINIMUM ROW WRITE TIME

$$T_{RW} = \frac{11064\ Cycles}{7.37\ MHz \times (1 + 0.05) \times (1 - 0.00375)} = 1.435 ms$$

The maximum row write time is equal to Equation 5-3.

EQUATION 5-3: MAXIMUM ROW WRITE TIME

$$T_{RW} = \frac{11064\ Cycles}{7.37\ MHz \times (1 - 0.05) \times (1 - 0.00375)} = 1.586 ms$$

Setting the WR bit (NVMCON<15>) starts the operation and the WR bit is automatically cleared when the operation is finished.

REGISTER 11-36: RPINR36: PERIPHERAL PIN SELECT INPUT REGISTER 36

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	IC16R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	IC15R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **IC16R<6:0>:** Assign Input Capture 16 (IC16) to the Corresponding RPn/RPIn Pin bits (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP127
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **IC15R<6:0>:** Assign Input Capture 15 (IC15) to the Corresponding RPn/RPIn Pin bits (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP127
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

NOTES:

REGISTER 21-8: CxEC: ECANx TRANSMIT/RECEIVE ERROR COUNT REGISTER

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
TERRCNT<7:0>							
bit 15							bit 8

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
RERRCNT<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **TERRCNT<7:0>:** Transmit Error Count bits

bit 7-0 **RERRCNT<7:0>:** Receive Error Count bits

REGISTER 21-9: CxCFG1: ECANx BAUD RATE CONFIGURATION REGISTER 1

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SJW<1:0>		BRP<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

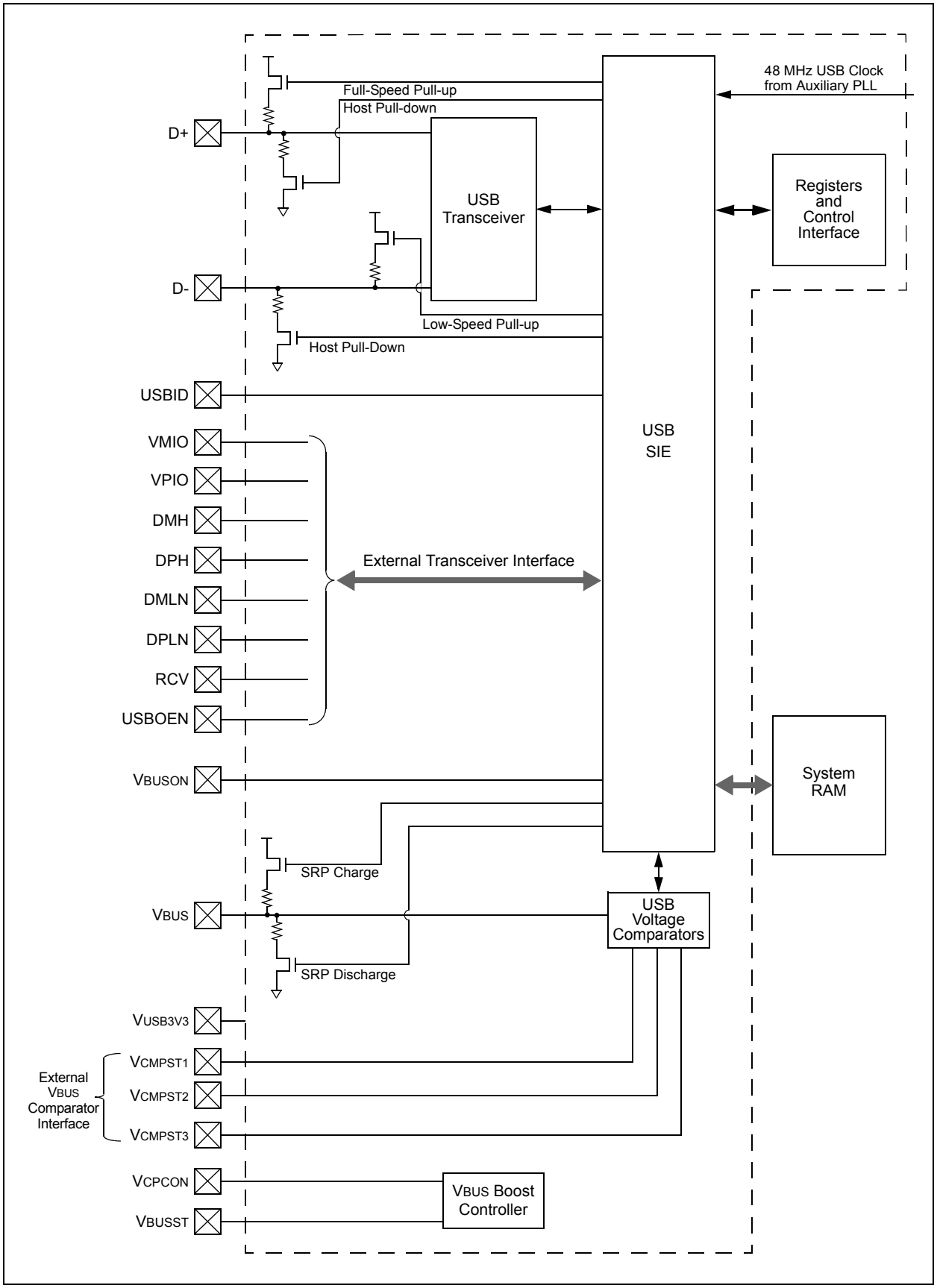
bit 7-6 **SJW<1:0>:** Synchronization Jump Width bits

11 = Length is 4 x TQ
10 = Length is 3 x TQ
01 = Length is 2 x TQ
00 = Length is 1 x TQ

bit 5-0 **BRP<5:0>:** Baud Rate Prescaler bits

11 1111 = TQ = 2 x 64 x 1/FCAN
•
•
•
00 0010 = TQ = 2 x 3 x 1/FCAN
00 0001 = TQ = 2 x 2 x 1/FCAN
00 0000 = TQ = 2 x 1 x 1/FCAN

FIGURE 22-1: USB INTERFACE DIAGRAM



REGISTER 25-2: CMxCON: COMPARATOR x CONTROL REGISTER (CONTINUED)

bit 4 **CREF:** Comparator Reference Select bit (VIN+ input)
1 = VIN+ input connects to internal CVREFIN voltage
0 = VIN+ input connects to CxIN1+ pin

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **CCH<1:0>:** Comparator Channel Select bits
11 = VIN- input of comparator connects to IVREF
10 = VIN- input of comparator connects to CXIN3- pin
01 = VIN- input of comparator connects to CXIN1- pin
00 = VIN- input of comparator connects to CXIN2- pin

REGISTER 26-10: ALRMVAL (WHEN ALRMPTR<1:0> = 00): ALARM MINUTES AND SECONDS VALUE REGISTER

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	MINTEN<2:0>			MINONE<3:0>			
bit 15							bit 8

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	SECTEN<2:0>			SECONE<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **MINTEN<2:0>:** Binary Coded Decimal Value of Minute's Tens Digit bits
Contains a value from 0 to 5.

bit 11-8 **MINONE<3:0>:** Binary Coded Decimal Value of Minute's Ones Digit bits
Contains a value from 0 to 9.

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **SECTEN<2:0>:** Binary Coded Decimal Value of Second's Tens Digit bits
Contains a value from 0 to 5.

bit 3-0 **SECONE<3:0>:** Binary Coded Decimal Value of Second's Ones Digit bits
Contains a value from 0 to 9.

27.0 PROGRAMMABLE CYCLIC REDUNDANCY CHECK (CRC) GENERATOR

Note 1: This data sheet summarizes the features of the dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 27. "Programmable Cyclic Redundancy Check (CRC)"** (DS70346) of the "*dsPIC33E/PIC24E Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The programmable CRC generator offers the following features:

- User-Programmable (up to 32nd order) Polynomial CRC Equation
- Interrupt Output
- Data FIFO

The programmable CRC generator provides a hardware implemented method of quickly generating checksums for various networking and security applications. It offers the following features:

- User-Programmable CRC Polynomial Equation, up to 32 bits
- Programmable Shift Direction (little or big-endian)
- Independent Data and Polynomial Lengths
- Configurable Interrupt Output
- Data FIFO

A simplified block diagram of the CRC generator is shown in Figure 27-1. A simple version of the CRC shift engine is shown in Figure 27-2.

FIGURE 27-1: PROGRAMMABLE CRC BLOCK DIAGRAM

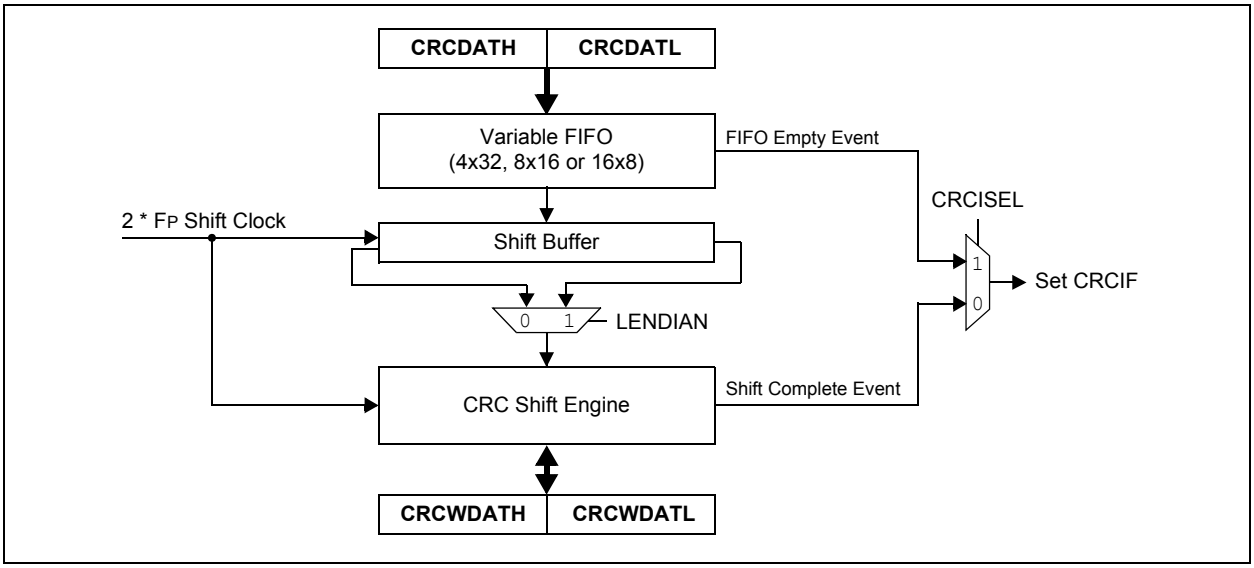
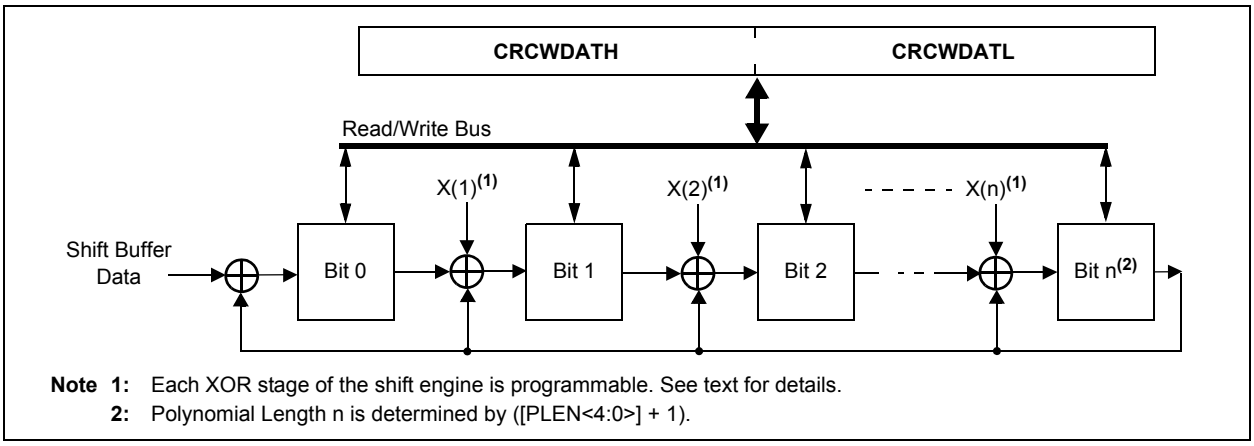


FIGURE 27-2: CRC SHIFT ENGINE DETAIL



Note 1: Each XOR stage of the shift engine is programmable. See text for details.

2: Polynomial Length n is determined by ([PLEN<4:0>] + 1).

NOTES:

TABLE 30-2: INSTRUCTION SET OVERVIEW

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles(2)	Status Flags Affected
1	ADD	ADD	Acc(1)	Add Accumulators	1	1	OA,OB,SA,SB
		ADD	f	f = f + WREG	1	1	C,DC,N,OV,Z
		ADD	f,WREG	WREG = f + WREG	1	1	C,DC,N,OV,Z
		ADD	#lit10,Wn	Wd = lit10 + Wd	1	1	C,DC,N,OV,Z
		ADD	Wb,Ws,Wd	Wd = Wb + Ws	1	1	C,DC,N,OV,Z
		ADD	Wb,#lit5,Wd	Wd = Wb + lit5	1	1	C,DC,N,OV,Z
		ADD	Wso,#Slit4,Acc	16-bit Signed Add to Accumulator	1	1	OA,OB,SA,SB
2	ADDC	ADDC	f	f = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	f,WREG	WREG = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	#lit10,Wn	Wd = lit10 + Wd + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,Ws,Wd	Wd = Wb + Ws + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,#lit5,Wd	Wd = Wb + lit5 + (C)	1	1	C,DC,N,OV,Z
3	AND	AND	f	f = f .AND. WREG	1	1	N,Z
		AND	f,WREG	WREG = f .AND. WREG	1	1	N,Z
		AND	#lit10,Wn	Wd = lit10 .AND. Wd	1	1	N,Z
		AND	Wb,Ws,Wd	Wd = Wb .AND. Ws	1	1	N,Z
		AND	Wb,#lit5,Wd	Wd = Wb .AND. lit5	1	1	N,Z
4	ASR	ASR	f	f = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	f,WREG	WREG = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	Ws,Wd	Wd = Arithmetic Right Shift Ws	1	1	C,N,OV,Z
		ASR	Wb,Wns,Wnd	Wnd = Arithmetic Right Shift Wb by Wns	1	1	N,Z
		ASR	Wb,#lit5,Wnd	Wnd = Arithmetic Right Shift Wb by lit5	1	1	N,Z
5	BCLR	BCLR	f,#bit4	Bit Clear f	1	1	None
		BCLR	Ws,#bit4	Bit Clear Ws	1	1	None
6	BRA	BRA	C,Expr	Branch if Carry	1	1 (4)	None
		BRA	GE,Expr	Branch if greater than or equal	1	1 (4)	None
		BRA	GEU,Expr	Branch if unsigned greater than or equal	1	1 (4)	None
		BRA	GT,Expr	Branch if greater than	1	1 (4)	None
		BRA	GTU,Expr	Branch if unsigned greater than	1	1 (4)	None
		BRA	LE,Expr	Branch if less than or equal	1	1 (4)	None
		BRA	LEU,Expr	Branch if unsigned less than or equal	1	1 (4)	None
		BRA	LT,Expr	Branch if less than	1	1 (4)	None
		BRA	LTU,Expr	Branch if unsigned less than	1	1 (4)	None
		BRA	N,Expr	Branch if Negative	1	1 (4)	None
		BRA	NC,Expr	Branch if Not Carry	1	1 (4)	None
		BRA	NN,Expr	Branch if Not Negative	1	1 (4)	None
		BRA	NOV,Expr	Branch if Not Overflow	1	1 (4)	None
		BRA	NZ,Expr	Branch if Not Zero	1	1 (4)	None
		BRA	OA,Expr(1)	Branch if Accumulator A overflow	1	1 (4)	None
		BRA	OB,Expr(1)	Branch if Accumulator B overflow	1	1 (4)	None
		BRA	OV,Expr(1)	Branch if Overflow	1	1 (4)	None
		BRA	SA,Expr(1)	Branch if Accumulator A saturated	1	1 (4)	None
		BRA	SB,Expr(1)	Branch if Accumulator B saturated	1	1 (4)	None
		BRA	Expr	Branch Unconditionally	1	4	None
		BRA	Z,Expr	Branch if Zero	1	1 (4)	None
		BRA	Wn	Computed Branch	1	4	None
7	BSET	BSET	f,#bit4	Bit Set f	1	1	None
		BSET	Ws,#bit4	Bit Set Ws	1	1	None

Note 1: This instruction is available in dsPIC33EPXXX(GP/MC/MU)806/810/814 devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles(2)	Status Flags Affected
8	BSW	BSW.C Ws,Wb	Write C bit to Ws<Wb>	1	1	None
		BSW.Z Ws,Wb	Write Z bit to Ws<Wb>	1	1	None
9	BTG	BTG f,#bit4	Bit Toggle f	1	1	None
		BTG Ws,#bit4	Bit Toggle Ws	1	1	None
10	BTSC	BTSC f,#bit4	Bit Test f, Skip if Clear	1	1 (2 or 3)	None
		BTSC Ws,#bit4	Bit Test Ws, Skip if Clear	1	1 (2 or 3)	None
11	BTSS	BTSS f,#bit4	Bit Test f, Skip if Set	1	1 (2 or 3)	None
		BTSS Ws,#bit4	Bit Test Ws, Skip if Set	1	1 (2 or 3)	None
12	BTST	BTST f,#bit4	Bit Test f	1	1	Z
		BTST.C Ws,#bit4	Bit Test Ws to C	1	1	C
		BTST.Z Ws,#bit4	Bit Test Ws to Z	1	1	Z
		BTST.C Ws,Wb	Bit Test Ws<Wb> to C	1	1	C
		BTST.Z Ws,Wb	Bit Test Ws<Wb> to Z	1	1	Z
13	BTSTS	BTSTS f,#bit4	Bit Test then Set f	1	1	Z
		BTSTS.C Ws,#bit4	Bit Test Ws to C, then Set	1	1	C
		BTSTS.Z Ws,#bit4	Bit Test Ws to Z, then Set	1	1	Z
14	CALL	CALL lit23	Call subroutine	2	4	SFA
		CALL Wn	Call indirect subroutine	1	4	SFA
		CALL.L Wn	Call indirect subroutine (long address)	1	4	SFA
15	CLR	CLR f	f = 0x0000	1	1	None
		CLR WREG	WREG = 0x0000	1	1	None
		CLR Ws	Ws = 0x0000	1	1	None
		CLR Acc,Wx,Wxd,Wy,Wyd,AWB(1)	Clear Accumulator	1	1	OA,OB,SA,SB
16	CLRWDT	CLRWDT	Clear Watchdog Timer	1	1	WDTO,Sleep
17	COM	COM f	$f = \overline{f}$	1	1	N,Z
		COM f,WREG	$WREG = \overline{f}$	1	1	N,Z
		COM Ws,Wd	$Wd = \overline{Ws}$	1	1	N,Z
18	CP	CP f	Compare f with WREG	1	1	C,DC,N,OV,Z
		CP Wb,#lit8	Compare Wb with lit8	1	1	C,DC,N,OV,Z
		CP Wb,Ws	Compare Wb with Ws (Wb – Ws)	1	1	C,DC,N,OV,Z
19	CP0	CP0 f	Compare f with 0x0000	1	1	C,DC,N,OV,Z
		CP0 Ws	Compare Ws with 0x0000	1	1	C,DC,N,OV,Z
20	CPB	CPB f	Compare f with WREG, with Borrow	1	1	C,DC,N,OV,Z
		CPB Wb,#lit8	Compare Wb with lit8, with Borrow	1	1	C,DC,N,OV,Z
		CPB Wb,Ws	Compare Wb with Ws, with Borrow (Wb – Ws – $\overline{C}$)	1	1	C,DC,N,OV,Z
21	CPSEQ	CPSEQ Wb,Wn	Compare Wb with Wn, skip if =	1	1 (2 or 3)	None
	CPBEQ	CPBEQ Wb,Wn,Expr	Compare Wb with Wn, branch if =	1	1 (5)	None
22	CPSGT	CPSGT Wb,Wn	Compare Wb with Wn, skip if >	1	1 (2 or 3)	None
	CPBGT	CPBGT Wb,Wn,Expr	Compare Wb with Wn, branch if >	1	1 (5)	None
23	CPSLT	CPSLT Wb,Wn	Compare Wb with Wn, skip if <	1	1 (2 or 3)	None
	CPBLT	CPBLT Wb,Wn,Expr	Compare Wb with Wn, branch if <	1	1 (5)	None
24	CPSNE	CPSNE Wb,Wn	Compare Wb with Wn, skip if ≠	1	1 (2 or 3)	None
	CPBNE	CPBNE Wb,Wn,Expr	Compare Wb with Wn, branch if ≠	1	1 (5)	None

Note 1: This instruction is available in dsPIC33EPXXX(GP/MC/MU)806/810/814 devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 32-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	VOL	**Output Low Voltage** I/O Pins: 4x Sink Driver Pins – All I/O Pins except OSC2 and SOSCO	—	—	0.4	V	IOL ≤ 10 mA, VDD = 3.3V
		Output Low Voltage I/O Pins: 8x Sink Driver Pins – OSC2 and SOSCO	—	—	0.4	V	IOL ≤ 15 mA, VDD = 3.3V
DO20	VOH	**Output High Voltage** I/O Pins: 4x Sink Driver Pins – All I/O Pins except OSC2 and SOSCO	2.4	—	—	V	IOH ≥ -10 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 8x Sink Driver Pins – OSC2 and SOSCO	2.4	—	—	V	IOH ≥ -15 mA, VDD = 3.3V
DO20A	VOH1	**Output High Voltage** I/O Pins: 4x Sink Driver Pins – All I/O Pins except OSC2 and SOSCO	1.5(1)	—	—	V	IOH ≥ -14 mA, VDD = 3.3V
			2.0(1)	—	—		IOH ≥ -12 mA, VDD = 3.3V
			3.0(1)	—	—		IOH ≥ -7 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 8x Sink Driver Pins – OSC2 and SOSCO	1.5(1)	—	—	V	IOH ≥ -22 mA, VDD = 3.3V
			2.0(1)	—	—		IOH ≥ -18 mA, VDD = 3.3V
			3.0(1)	—	—		IOH ≥ -10 mA, VDD = 3.3V

Note 1: Parameters are characterized, but not tested.

TABLE 32-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V(2) (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.(1)**	**Typ.**	**Max.**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD Transition High-to-Low	2.7	—	2.9	V	VDD

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

2: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules: ADC, Comparator and DAC will have degraded performance. Device functionality is tested but not characterized.

32.2 AC Characteristics and Timing Parameters

This section defines the dsPIC33EPXXX(GP/MC/MU)806/810/814 and PIC24EPXXX(GP/GU)810/814 AC characteristics and timing parameters.

TABLE 32-14: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended Operating voltage VDD range as described in **Section 32.1 "DC Characteristics"**.

FIGURE 32-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

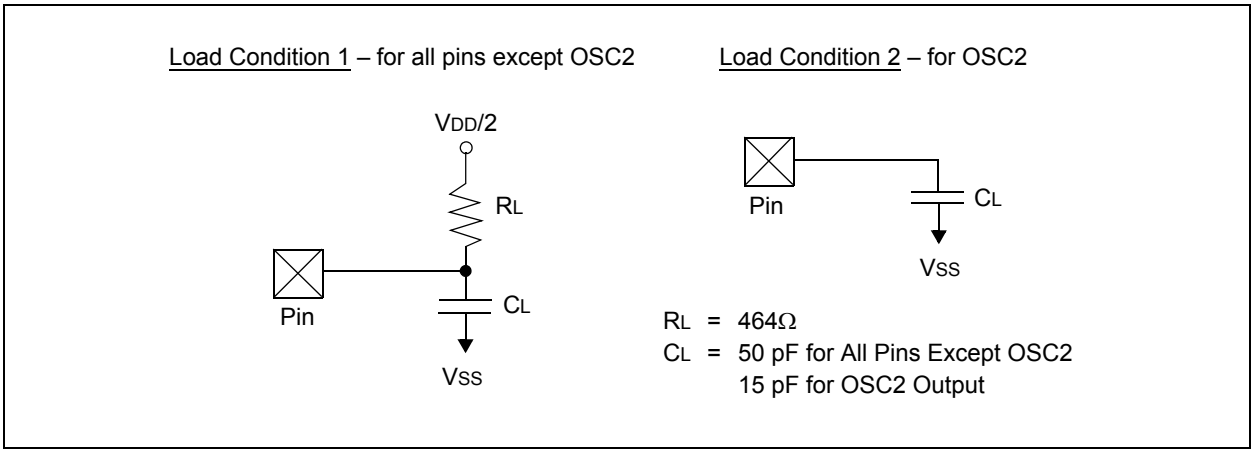
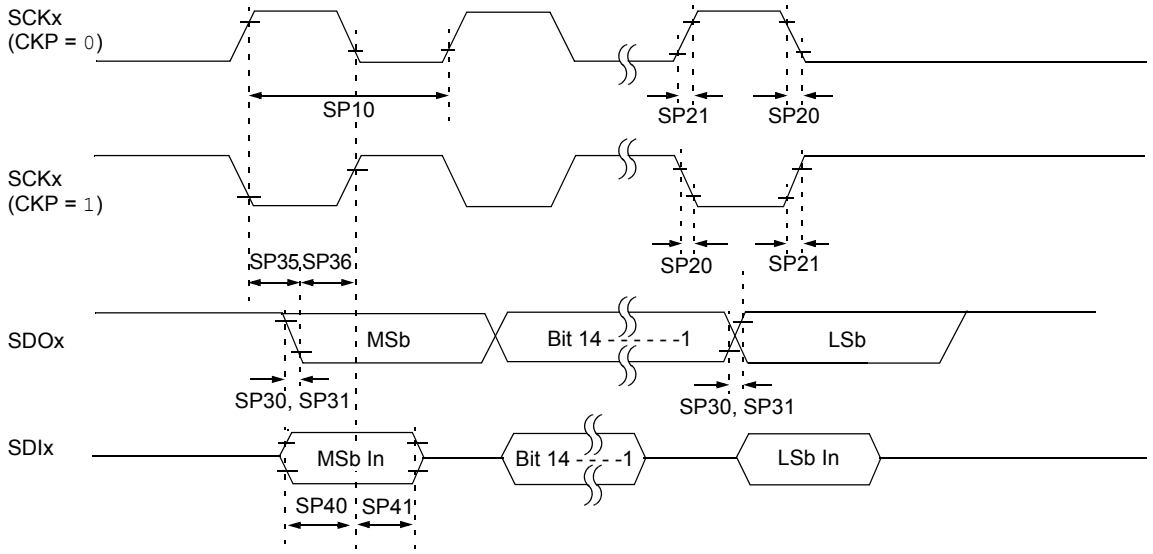


TABLE 32-15: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DO50	COSCO	OSC2 Pin	—	—	15	pF	In XT and HS modes when external clock is used to drive OSC1
DO56	CIO	All I/O Pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I^2C™ mode

FIGURE 32-18: SPI1, SPI3 AND SPI4 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 32-1 for load conditions.

TABLE 32-36: SPI1, SPI3 AND SPI4 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	TscP	Maximum SCKx Frequency	—	—	9	MHz	-40ºC to +125ºC and see **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid After SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

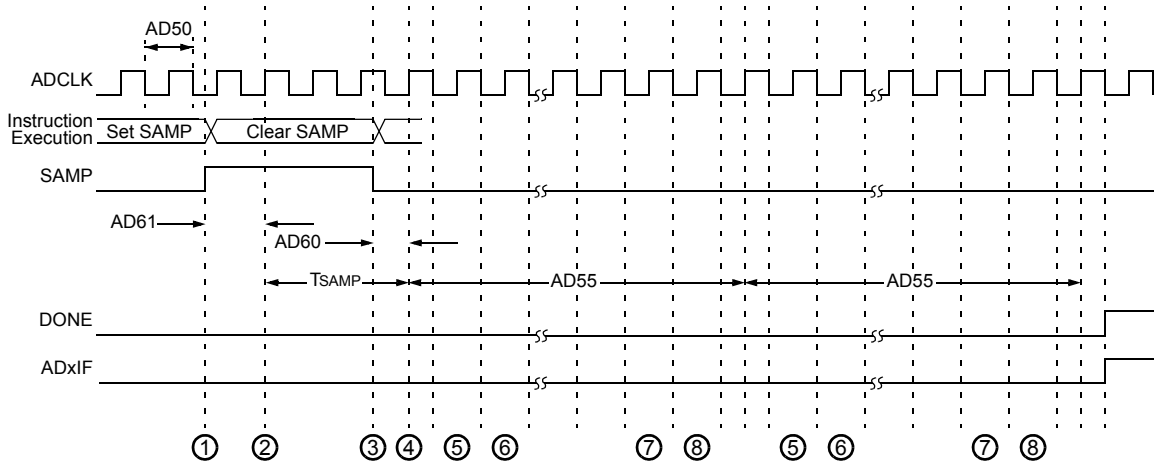
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 111 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 32-38: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000, SSRCG = 0)



(1) – Software sets ADx1CON1. SAMP to start sampling.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70621) of the *"dsPIC33E/PIC24E Family Reference Manual"*.

(3) – Software clears ADxCON1. SAMP to start conversion.

(4) – Sampling ends, conversion sequence starts.

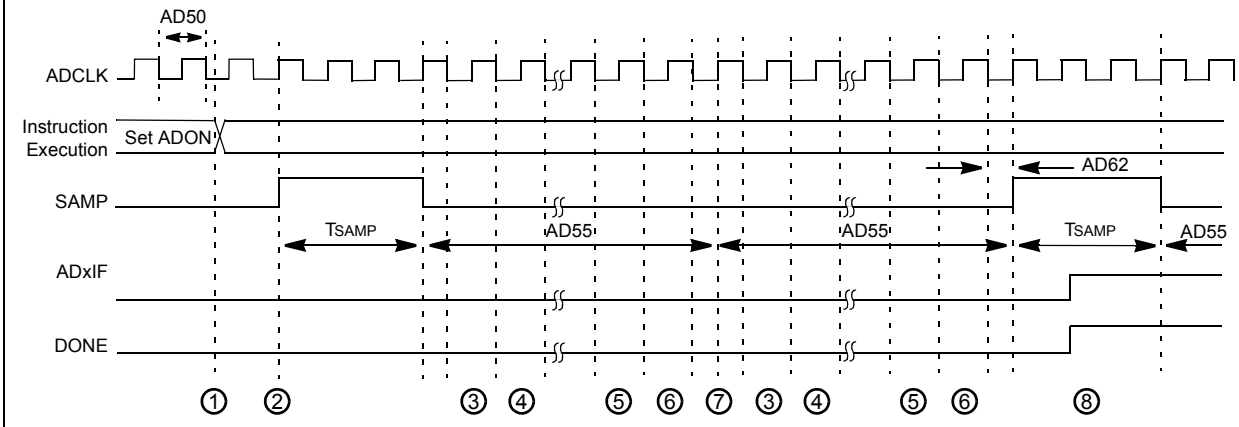
(5) – Convert bit 9.

(6) – Convert bit 8.

(7) – Convert bit 0.

(8) – One TAD for end of conversion.

FIGURE 32-39: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SSRCG = 0, SAMC<4:0> = 00010)



(1) – Software sets ADxCON1. ADON to start AD operation.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70621) of the *"dsPIC33E/PIC24E Family Reference Manual"*.

(3) – Convert bit 9.

(4) – Convert bit 8.

(5) – Convert bit 0.

(6) – One TAD for end of conversion.

(7) – Begin conversion of next channel.

(8) – Sample for time specified by SAMC<4:0>.

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